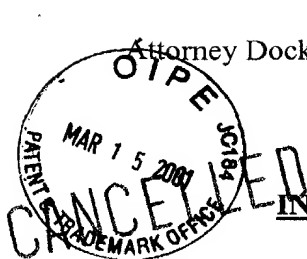


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PATENT



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re U.S. Patent Application of:  
M. Takeya et al.

Serial No.: 09/760,959

Filed: January 16, 2001

For: SEMICONDUCTOR DEVICE

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) Examiner: T. Nguyen  
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) Group Art Unit: 2818  
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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

1. (Once Amended) An electronic circuit device, comprising: [including] a plurality of circuit boards which have electronic parts mounted thereon [and are three-dimensionally assembled, characterized in that said], the plurality of circuit boards area stacked in the thickness direction [through] by metal pieces [at least one ends of which are] fixed [to] between the circuit boards wherein opposite ends of each metal piece are fixed to opposing circuit boards by materials which have different melting points.

3. (Once Amended) An electronic circuit device, comprising: [including] a plurality of circuit boards which have electronic parts mounted thereon [and are three-dimensionally assembled, characterized in that said], the plurality of circuit boards are assembled in the thickness direction [through] by spacers [each of which comprises], each spacer comprising a metal piece, and one end of each [metal piece] spacer is fixed to one circuit board by a solder while [the] another other end of [said metal piece] each spacer is fixed to another circuit board by a conductive adhesive agent wherein the conductive adhesive agent has [having] a melting point lower than the solder.

4. (Once Amended) The electronic circuit device as claimed in claim 3, wherein [said adhesive agent is conductive adhesive agent, and said] the circuit boards are electrically connected to each other by [said metal pieces] the spacers.

5. (Once Amended) An electronic circuit device, comprising: [including] a plurality of circuit boards which have electronic parts mounted thereon [and are three-dimensionally assembled, characterized in that said], the plurality of circuit boards are assembled in the thickness direction [through] by spacers wherein each [of which] spacer comprises a metal piece, and [both the ends of each metal piece are fixed to said circuit boards at both sides of the metal piece by solder] one end of the spacer is fixed to one circuit board by a first solder while another end of the spacer is fixed to another circuit board by a second solder wherein the first solder has a higher melting point than the second solder.

7. (Once Amended) The electronic circuit device of claim 5, wherein [said] the electronic parts are soldered to [said] the circuit boards by [solder material having the same melting point as the solder material having a higher melting point in said solder materials used to fix both the ends of said metal pieces to said circuit boards] the first solder.

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